



Material Content Data Sheet



Sales Product Name				IPD50N06S4L-12		Issued		20. July 2018	
MA#				MA001064856					
Package				PG-TO252-3-11		Weight*		371.83 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.345	0.36	0.36	3617	3617	
leadframe	non noble metal	iron	7439-89-6	0.215	0.06		579		
	inorganic material	phosphorus	7723-14-0	0.065	0.02		174		
	non noble metal	copper	7440-50-8	215.017	57.82	57.90	578272	579025	
wire	non noble metal	aluminium	7429-90-5	20.241	5.44	5.44	54437	54437	
encapsulation	organic material	carbon black	1333-86-4	1.103	0.30		2966		
	plastics	epoxy resin	-	19.299	5.19		51902		
	inorganic material	silicondioxide	60676-86-0	89.877	24.17	29.66	241717	296585	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10059	10059	
plating	non noble metal	nickel	7440-02-0	0.091	0.02		244		
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	245	
solder	noble metal	silver	7440-22-4	0.041	0.01		110		
	non noble metal	tin	7440-31-5	0.033	0.01		88		
	non noble metal	lead	7439-92-1	1.558	0.42	0.44	4191	4389	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		52		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		15		
	non noble metal	copper	7440-50-8	19.177	5.16	5.17	51576	51643	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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